L Number	Hits	Search Text	DB	Time stamp
11	0	6124769.pn and alumina and ruthenium	USPAT; US-PGPUB;	2004/05/20 13:56
17	1	"3353124".PN.	IBM_TDB USPAT	2004/05/20
19	6	(29/612).ccls. and ((thermistor near chip) or (chip near resistor)) and glass	USPAT; US-PGPUB; IBM TDB	2004/05/20 15:25
25	1	(333/172).ccls. and ((thermistor near chip) or (chip near resistor)) and (alumina adj substrate) and ruthenium and stack\$3	USPAT; US-PGPUB; IBM_TDB	2004/05/20 15:29
_	608	29/611.ccls.	USPAT; US-PGPUB; IBM TDB	2003/06/04 19:12
_	586	29/\$.ccls. and substrate and ((etch or etched or etching) with foil)	USPAT; US-PGPUB; IBM TDB	2003/06/04 15:56
-	0	29/\$.ccls. and (photoresistive with substrate) and ((etch or etched or etching) with foil)	USPĀT; US-PGPUB;	2003/06/04 15:56
-	. 4	29/\$.ccls. and (photoresistive and substrate) and ((etch or etched or etching) with foil)	IBM_TDB USPAT; US-PGPUB;	2003/06/04 15:57
	11	29/\$.ccls. and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching) with	IBM_TDB USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:03
-	17	foil) 29/\$.ccls. and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching) and	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:11
	100	foil) resistor and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching) and	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:12
	48	foil) ((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or	USPAT; US-PGPUB; IBM_TDB	2003/06/04 19:49
_	7	etched or etching) and foil) ("4336320" "5466963" "5849355" "5872038" "5935642" "5960270" "5994997").PN.	USPAT	2003/06/04
-	8	3994997 "4610810" "4870746" "5162144" "5260170" "5338567" "5347258" "5792594") PN	USPAT	2003/06/04 16:30
_	28	((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and (etch or etched or etching) and foil and width	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:42
_	28	((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and (etch or etched or etching) and foil with (thick	USPAT; US-PGPUB; IBM_TDB	2003/06/04
	28	or thickness or width) ((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and (etch or etched or etching) and (foil with (thick	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:48
_	32	or thickness or width)) ((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching or polishing) with foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 19:42

_	17	("2945180" "3808576" "3813631"	USPAT	2003/06/04
		"4174513" "4737747" "4888574"		17:03
		"4892776" "5336391" "5422313"		
		"5483217" "5756971" "5864281"		
		"5907273" "5994997" "6141870"		
		"6232042" "6248612").PN.		
	14	l	USPAT;	2003/06/05
		((etch or etched or etching) with foil)	US-PGPUB;	09:15
		and resistor	IBM TDB	05.13
	20	(338/306-309).ccls. and substrate and	USPAT;	2003/06/05
_	38			09:16
		((etch or etched or etching) with foil)	US-PGPUB;	09:16
	_	and resistor	IBM_TDB	2222425425
-	3	(338/306-309).ccls. and substrate and	USPAT;	2003/06/05
	1	((etch or etched or etching) with foil)	US-PGPUB;	09:18
		and ((method or processor assembling or	IBM_TDB	
		making or manufacturing or step) adj		
		resistor)		
-	79		USPAT;	2003/06/05
	•	((etch or etched or etching) with foil)	US-PGPUB; .	09:19
1	1		IBM TDB	
_	13	(430/313,315,324).ccls. and substrate and	USPĀT;	2003/06/05
		((etch or etched or etching) with foil)	US-PGPUB;	09:19
		and resistor	IBM TDB	
_	1	(438/462,977).ccls. and substrate and	USPAT;	2003/06/05
	1	(etch or etched or etching) and foil and	US-PGPUB;	09:20
		resistor	IBM TDB	
1_	18	3669022.URPN.	USPAT	2003/06/05
-	10	5005022.0KFN.	001111	10:42
	,	C222042 HDDN	USPAT	2003/06/05
-	1	6232042.URPN.	USPAI	1
		64.0.40.00	11077	10:46
-	1	6194990.pn.	USPAT;	2003/06/05
			US-PGPUB;	11:20
			IBM_TDB	
-	11	("3719508" "4786564" "4888574"	USPAT	2003/06/05
		"4892776" "5053318" "5336391"		10:48
		"5347258" "5403672" "5560812"		
		"5679498" "6171921").PN.		
_	11	4297670.URPN.	USPAT	2003/06/05
				10:50
_	12	("2945180" "3808576" "3813631"	USPAT	2003/06/05
		"4174513" "4888574" "4892776"		10:51
	1	"5336391" "5422313" "5483217"		
	1	"5756971" "5864281" "5907273").PN.		
	3	6194990.URPN.	USPAT	2003/06/05
		0194990.0KFN.	OSIAI	10:52
	11	laminated add resistor	USPAT;	2003/06/05
1 -	1 11	laminated adj resistor	US-PGPUB;	11:21
1				11.21
			IBM_TDB	2003/05/05
-	1988	chip adj resistor	USPAT;	2003/06/05
	1		US-PGPUB;	11:30
			IBM_TDB	2002/06/25
-	570	(chip adj resistor) and glass	USPAT;	2003/06/05
]		US-PGPUB;	11:22
			IBM_TDB	/
-	328	(chip adj resistor) and glass and	USPAT;	2003/06/05
		terminal	US-PGPUB;	11:22
	1		IBM_TDB	ļ
-	126	(chip adj resistor) and glass and	USPĀT;	2003/06/05
		terminal and nickel	US-PGPUB;	11:23
			IBM TDB	
_	126	(method or process or manufacturing or	USPAT;	2003/06/05
		making or producing or steps) and (chip	US-PGPUB;	11:24
		adj resistor) and glass and terminal and	IBM TDB	
		nickel		
	11		USPAT;	2003/06/05
1 -	1 11	making or producing or steps) adj (chip	US-PGPUB;	11:24
			1	11.23
		adj resistor) and glass and terminal and	IBM_TDB	
	_	nickel	II CDAE	2002/06/25
-	5	("3167451" "4437140" "4684916"	USPAT	2003/06/05
		"5510594" "5680092").PN.	L	11:28

_	30	(29/610.1,620,621).ccls. and (chip adj resistor)	USPAT; US-PGPUB;	2003/06/05 11:39
_	10	4267634.URPN.	IBM_TDB USPAT	2003/06/05 11:36
-	5	(29/610.1,620,621).ccls. and (chip adj resistor) and multilayer	USPAT; US-PGPUB;	2003/06/05 11:40
_	11	(338/308,309,332).ccls. and (chip adj resistor) and multilayer	IBM_TDB USPAT; US-PGPUB;	2003/06/05 11:41
	13	5170146.URPN.	IBM_TDB USPAT	2003/06/05
-	10	5287083.URPN.	USPAT	11:42 2003/06/05
		4267634.pn. and glass	USPAT;	11:47 2003/06/05
-	1	420/034.pm. and grass	US-PGPUB; IBM TDB	13:32
-	10	4267634.URPN.	USPAT	2003/06/05
_	0	multilayered adj resistor	USPAT; US-PGPUB;	2003/06/05
	8	multi-layered near resistor	IBM_TDB USPAT;	2003/06/05
	•	matti layered hear lesistor	US-PGPUB; IBM TDB	13:20
-	32723	ceramic near glass	USPAT; US-PGPUB;	2003/06/05
	3649	(ceramic near glass) and resistor	IBM_TDB USPAT;	2003/06/05
	3045	(ceramic hear grass) and resistor	US-PGPUB; IBM TDB	13:21
_	81	(ceramic near glass) and (chip adj	USPAT; US-PGPUB;	2003/06/05 13:21
_	0	4267634.pn. and nickel	IBM_TDB USPAT;	2003/06/05
	Ů	120/03 rpm and 120/02	US-PGPUB; IBM TDB	13:36
_	3612	nickel with melting	USPAT; US-PGPUB;	2003/06/05 13:37
_	2226	nickel with (melting adj (point or	IBM_TDB USPAT;	2003/06/05
		temperature))	US-PGPUB; IBM_TDB	13:38
-	314	nickel near (melting adj (point or temperature))	USPAT; US-PGPUB;	2003/06/05 13:39
_	17	nickel near (melting adj (point or	IBM_TDB USPAT;	2003/06/05
		temperature)) and resistor	US-PGPUB; IBM_TDB	13:50
-	9	<pre>palladium near (melting adj (point or temperature)) and resistor</pre>	USPAT; US-PGPUB;	2003/06/05 13:51
_	0	(29/619).ccls. and (chip adj resistor)	IBM_TDB USPAT;	2003/06/05
		and multilayer	US-PGPUB; IBM_TDB	15:03
_	17	(29/611,610.1,619,620,621).ccls. and substrate and ((etch or etched or	USPAT; US-PGPUB;	2003/06/05 15:05
_	15	etching) with foil) and resistor (29/610.1,619,620,621).ccls. and	IBM_TDB USPAT;	2003/06/05
		substrate and ((etch or etched or etching) with foil) and resistor	US-PGPUB; IBM_TDB	15:08
_	31	(174/260).ccls. and substrate and ((etch or etched or etching) with foil) and	USPAT; US-PGPUB;	2003/06/05 15:08
_	19		IBM_TDB USPAT;	2003/06/05
		or etched or etching) with foil) and resistor and multilayer\$3 (huber near Louis).in. and power adj chip	US-PGPUB; IBM_TDB	15:09
-	2	(nuber hear Louis).in. and power adj chip adj resistor	USPAT; US-PGPUB; IBM TDB	2003/11/12 17:20
L		<u> </u>	T DM T DB	1

		## 40 00 10 II		10004/05/10
-	15	"5488348"	USPAT;	2004/05/18
			US-PGPUB;	18:05
	İ		IBM_TDB	
-	1	5488348.pn.	USPAT;	2004/05/18
			US-PGPUB;	18:11
			IBM TDB	
_	0	(95/31816).CCLS.	EPO	2004/05/18
		(50,01010,.0025.	22 0	18:12
	0	(WO95/31816).CCLS.	EPO	2004/05/18
_	0	(WO93/31616).CCL3.	EFO	
		/# 0 F 0 d 0 d C H \	770	18:12
-	0	("WO9531816").PN.	EPO	2004/05/18
				18:12
-	0	(("5303115") or ("3775725") or	EPO	2004/05/19
		("4924074")).PN.		13:55
_	6	(("5303115") or ("3775725") or	USPAT;	2004/05/19
		("4924074")).PN.	US-PGPUB;	13:55
		(DERWENT;	
			IBM TDB	
	2	(("5303115") or ("3775725") or	USPAT;	2004/05/19
_	3			
		("4924074")).PN.	US-PGPUB;	13:55
			IBM_TDB	
-	1	("6606023").PN.	USPAT;	2004/05/19
			US-PGPUB;	14:32
			IBM TDB	
_	0	("6311390").PN.	EPO	2004/05/19
		, , ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		15:27
I _	1	("6311390").PN.	USPAT;	2004/05/19
_	1	(6311390).PN.		
			US-PGPUB;	17:16
			IBM_TDB	
-	5	("5488348" "5493266" "6020808"	USPAT	2004/05/19
		"6040755" "6157289").PN.		15:29
_	5	(thermistor adj strip) and glass	USPAT;	2004/05/19
			US-PGPUB;	15:37
			IBM TDB	20.0.
_	48	(thermistor adj chip) and glass	USPAT;	2004/05/19
_	40	(chermiscor adj chip) and grass	US-PGPUB;	15:40
				15:40
			IBM_TDB	
-	13	(thermistor adj chip) and glass and	USPAT;	2004/05/19
		alumina	US-PGPUB;	15:40
]		IBM TDB	
_	1	(thermistor adj chip) and glass and	USPAT;	2004/05/19
		alumina and ruthenium	US-PGPUB;	16:12
			IBM TDB	1
1_	55	((thermistor adj chip) or (chip adj	USPAT;	2004/05/19
	33	resistor)) and glass and alumina and	US-PGPUB;	16:29
		· · · · · · · · · · · · · · · · · · ·		10.49
		ruthenium	IBM_TDB	0000/05/55
-	12	((thermistor adj chip) or (chip adj	USPAT;	2004/05/19
		resistor)) and glass and alumina and	US-PGPUB;	16:33
		ruthenium and stack\$3	IBM_TDB	
-	6	((thermistor adj chip) or (chip adj	USPAT;	2004/05/19
1	1	resistor)) and glass and (alumina adj	US-PGPUB;	16:34
1		substrate) and ruthenium and stack\$3	IBM TDB	
_	1	6311390.pn. and glass	USPAT;	2004/05/19
	1	ourrand draga	US-PGPUB;	17:16
	1		1	1/:10
	1 _	6221200	IBM_TDB	0004/05/50
-	0	6311390.pn. and glass and alumina	USPAT;	2004/05/19
			US-PGPUB;	17:16
1	}		IBM_TDB	
-	0	6311390.pn. and glass and ruthenium	USPAT;	2004/05/19
	1	<u> </u>	US-PGPUB;	17:17
1			IBM TDB	- · · - ·
! _	1	"3353124".PN.	_	2004/05/10
-	1	3333174 'KM'	USPAT	2004/05/19
	_	(#C2C0702#) PV		17:52
-	1	("6362723").PN.	USPAT;	2004/05/19
	t		US-PGPUB;	18:07
			IBM_TDB	1
-	6	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:13
		substrate) and ruthenium and stack\$3	IBM TDB	
L		,,		4

_	914	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and glass	US-PGPUB;	18:20
		-	IBM_TDB	ĺ
-	121	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:12
		substrate)	IBM_TDB	
-	33	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:25
		substrate) and ruthenium	IBM_TDB	
-	77	((thermistor near chip) or (chip near	USPAT;	2004/05/19
		resistor)) and (glass adj substrate)	US-PGPUB;	18:21
			IBM_TDB	
-	20	'	USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:25
		substrate) and ruthenium and plat\$3	IBM_TDB	
-	6	1 , , , , , , , , , , , , , , , , , , ,	USPAT;	2004/05/19
		resistor)) and glass and (alumina adj	US-PGPUB;	18:26
		substrate) and ruthenium and (nickel near	IBM_TDB	
		plat\$3)		